

2SJ530(L), 2SJ530(S)

Silicon P Channel MOS FET

REJ03G0880-0500 (Previous: ADE-208-655C) Rev.5.00 Sep 07, 2005

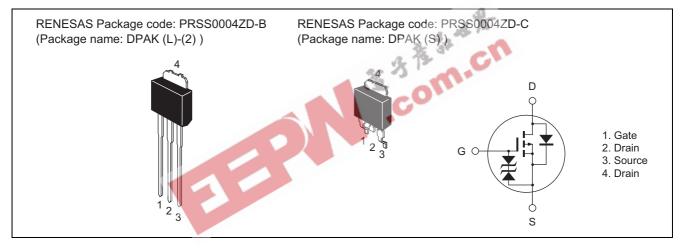
Description

High speed power switching

Features

- Low on-resistance
- $R_{DS(on)} = 0.08 \ \Omega \ typ.$
- 4 V gate drive devices.
- High speed switching.

Outline





Absolute Maximum Ratings

			(Ta = 25°C)
Item	Symbol	Value	Unit
Drain to source voltage	V _{DSS}	-60	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	ID	-15	A
Drain peak current	I _{D (pulse)} Note 1	-60	А
Body to drain diode reverse drain current	I _{DR}	-15	А
Avalanche current	I _{AP} Note 3	-15	А
Avalanche energy	E _{AR} Note 3	19	mJ
Channel dissipation	Pch Note 2	30	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. Value at Tc = 25°C

3. Value at Tch = 25° C, Rg $\geq 50 \Omega$

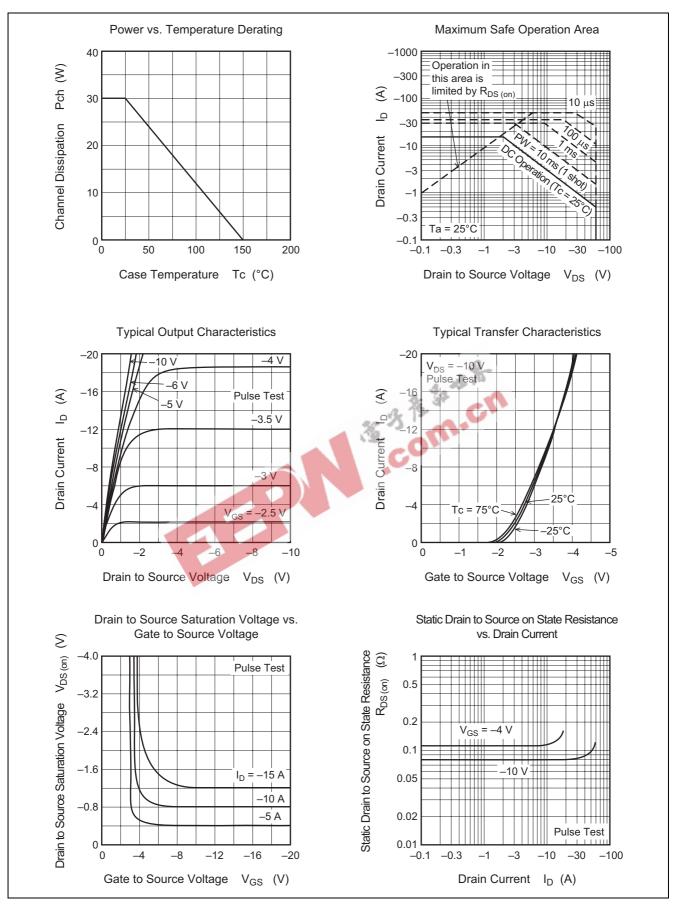
Electrical Characteristics

						(Ta = 25°C)
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V (BR) DSS	-60		_	V	$I_D = -10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR) GSS}$	±20	_	4	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}		a	-10	μA	$V_{DS} = -60 \text{ V}, \text{ V}_{GS} = 0$
Gate to source leak current	I _{GSS}		<u>x</u> -2	±10	μA	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Gate to source cutoff voltage	V _{GS (off)}	-1.0	3.	-2.0	V	$I_D = -1 \text{ mA}, V_{DS} = -10 \text{ V}$
Static drain to source on state resistance	R _{DS (on)}	+	0.08	0.10	Ω	$I_D = -8 \text{ A}, V_{GS} = -10 \text{ V}^{Note 4}$
Static drain to source on state resistance	R _{DS (on)}	-	0.11	0.16	Ω	$I_D = -8 \text{ A}, V_{GS} = -4 \text{ V}^{Note 4}$
Forward transfer admittance	y _{fs}	6.5	11		S	$I_D = -8 \text{ A}, V_{DS} = -10 \text{ V}^{Note 4}$
Input capacitance	Ciss	_	850		pF	$V_{DS} = -10 V$
Output capacitance	Coss	—	420		pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss		110		pF	f = 1 MHz
Turn-on delay time	t _{d (on)}	_	12		ns	$V_{GS} = -10 V$
Rise time	tr	_	75		ns	$I_{\rm D} = -8$ A
Turn-off delay time	t _{d (off)}	_	125		ns	$R_L = 3.75 \ \Omega$
Fall time	t _f	_	75		ns	
Body to drain diode forward voltage	V_{DF}	_	-1.1	_	V	$I_F = -15 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time	t _{rr}		70		ns	$I_F = -15 \text{ A}, V_{GS} = 0$
						di _F /dt = 50 A/µs

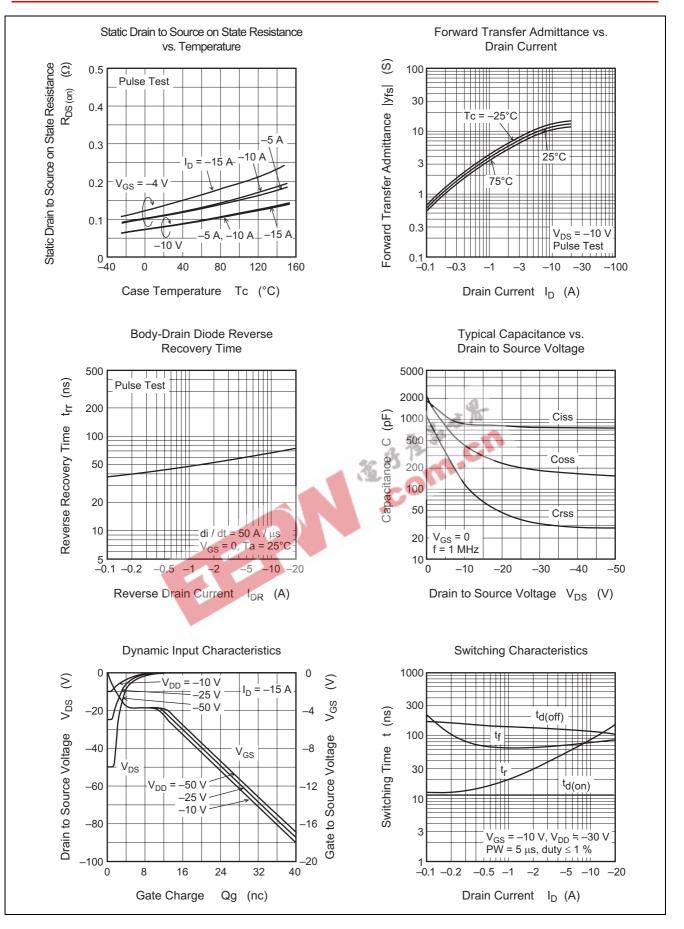
Note: 4. Pulse test



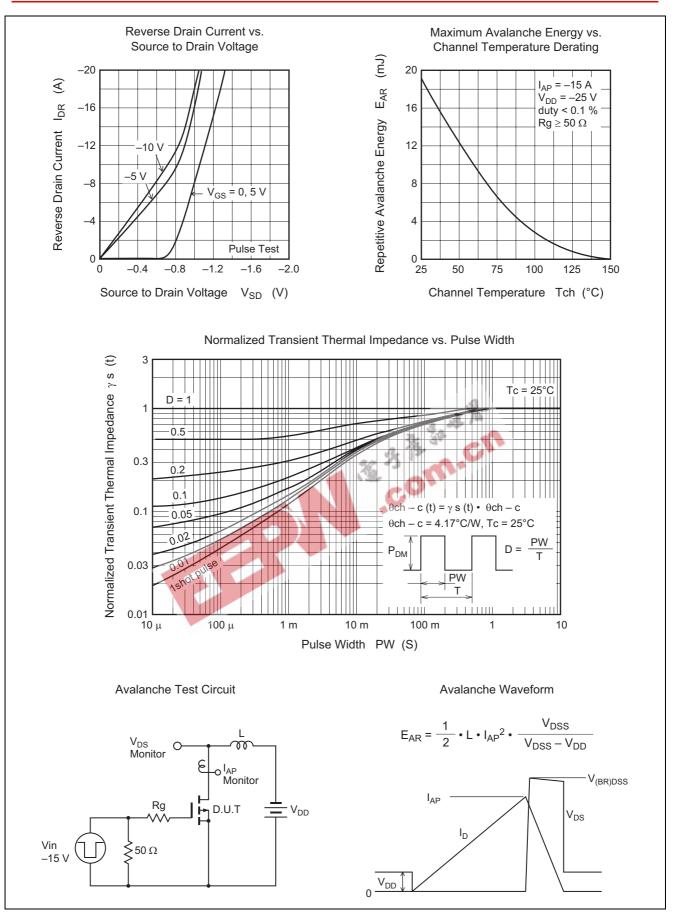
Main Characteristics





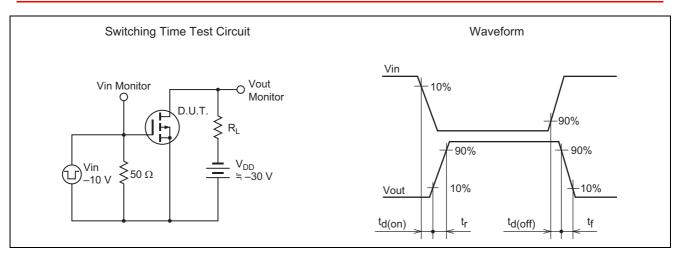








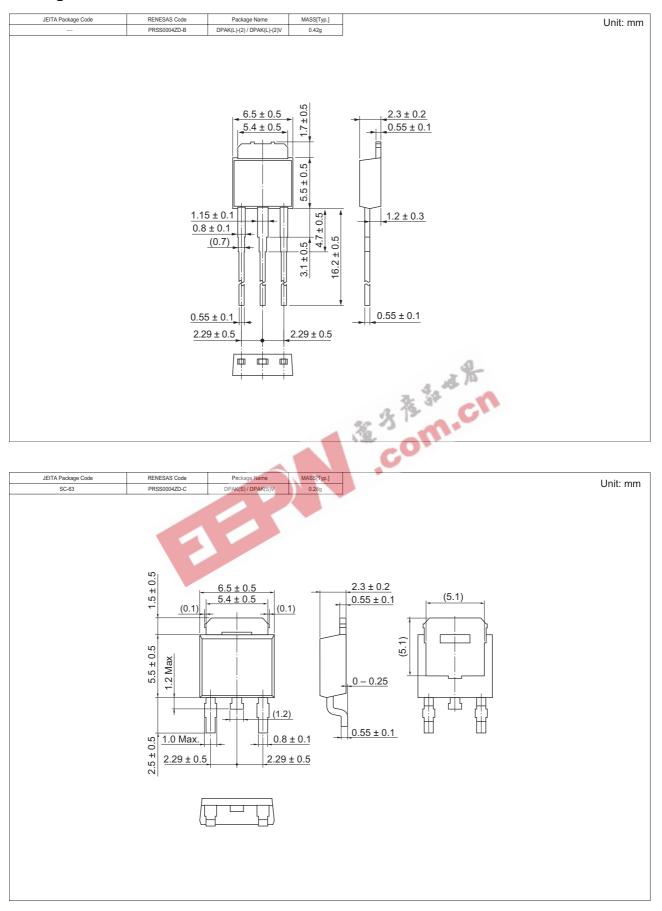
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Package Dimensions





Ordering Information

Part Name	Quantity	Shipping Container
2SJ530L-E	3200 pcs	Box (Sack)
2SJ530STL-E	3000 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.





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